

# Laboratories for Micro- and Nanotechnology

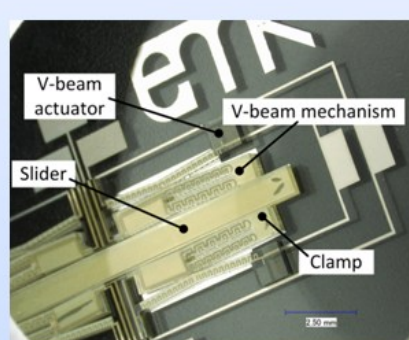
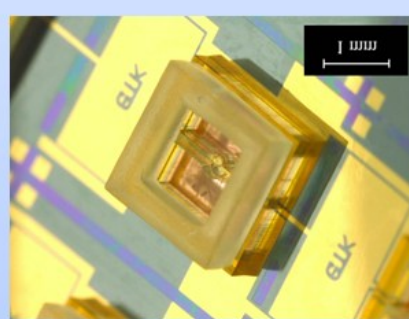
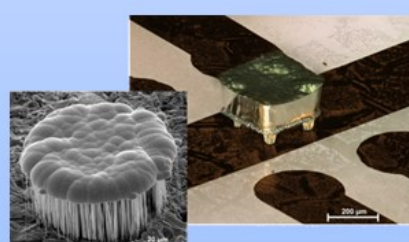
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TECHNISCHE  
UNIVERSITÄT  
DARMSTADT


## Cleanroom Laboratory

**Application examples**

- Micro relays and micro positioning systems
- Acceleration and gas flow sensors
- Electrical micro-nano contacts
- Bio cell interfaces
- Microfluidics
- RF MEMS
- Force and pressure sensors


**Sputtering**



**Alcatel**

- DC/ HF Sputtering with RF-Bias
- 4 Cathodes
- Al, Cr, Cu, SiO<sub>2</sub>
- Deposition Rates up to 1000 nm/min
- Vacuum Prechamber


**Vapour Deposition**



**Balzers BAK 600**

- Electron Beam and Resistance Evaporator
- Al, Cu, Cr, Ni, Ag, Ti, Au, Al<sub>2</sub>O<sub>3</sub>
- Thickness Control through Quartz Resonator


**Isotrop Etching**



**Muegge STP 2020**

- Remote Downstream Plasma Reactor for Polymer Etching (e.g. SU-8, BCB)
- O<sub>2</sub>, CF<sub>4</sub>, N<sub>2</sub>
- RF-Power: 3000 W at 13,56 MHz

**Anisotrop Etching**



**Plasma Technology RIE80**

- Parallel Plate Reactor for Substrate Cleaning and Polymer Etching
- O<sub>2</sub>, CF<sub>4</sub>, N<sub>2</sub>
- RF-Power: 300 W at 13,56 MHz

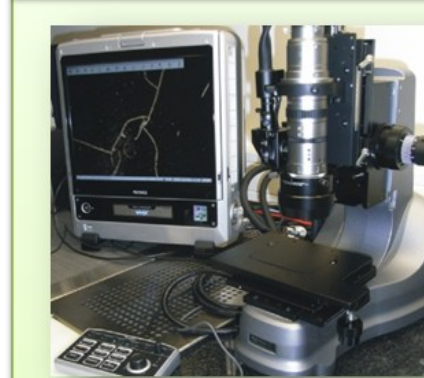
**Wire Bonder**



**F&K Delvotek 53xx-BDA Bonder**

- Ball Bonding down to 18 µm gold wire
- Deep access wedge bonding
- Automated y-axis for automated loops

**Optical Inspection**



**Keyence VHX-600**


- 3CCD Camera
- 54 Mio Pixel
- Magnification up to 1000x
- 3D Measurement Option
- Measurements of Structural Widths

~60 m<sup>2</sup> for surface coating, dry etching, packaging, characterization

~60 m<sup>2</sup> for photolithography, wet etching, electroplating

Classification:  
1000 - 100 within the laminar airflow boxes

**Surface Activation**



**Technics 300-E Plasma**

- Barrel Reactor for Substrate Cleaning and Surface Activation
- O<sub>2</sub>, CF<sub>4</sub>, N<sub>2</sub>
- RF-Power: 300 W at 13,56 MHz

**Spin Coater**



**SÜSS Delta 80 BM**

- Rotating Lid
- Up to 4000 rpm

**SÜSS LabSpin 6**

- Up to 8000 rpm

**Photo Resists**

- SU-8 2000/3000
- AZ 9260
- AZ 15, 40, 125 (n)XT

**Hotplates**



**2x Hotplate 400**

- Programmable Single Plate
- Up to 130 °C

**3x GESTIGKEIT PR 5-3T**

- Programmable Double Plate
- Up to 300 °C

**IR Oven**



**FH Zwickau**

- IR dry system for photoresist
- Up to 6" wafer
- Max. heat 130 °C
- Maximum substrate weight 150 g

**Mask Aligner**




**SÜSS MA 56 M**

- 350 W UV-Lamp
- Up to 4" Masks
- Manual Alignment
- Up to 20 mW/cm<sup>2</sup>
- Process Monitoring

**Filters**

- g, h, i - Line
- g, h - Line
- i - Line

**Developer**



**Sonosys 500**

- Frequency 1 MHz
- Power 50 - 500 W

**Multi-Bio-3D**

- Orbital Shaker

**Developer**

- mr-Dev 600
- MIF 326, 826
- AZ 400k

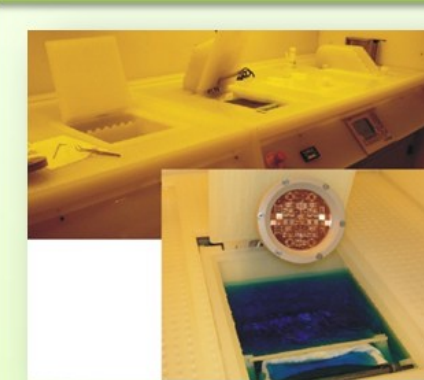
**Surface Profiler**



**DEKTAK 8 Profiler**

- Measurement of Layer Thickness and Surface Profile
- Range from 10 nm up to 1 mm
- Stylus Force up to 0,09 mg

**Micro Electroplating**



**M-O-T µGalv**

- Additive free Electrolytes
- Nickel (pH 4), Copper (acid)
- Currents up to 10 A
- Puls-Plating Option
- Plating rate up to 4 µm/min

**Micro & Nano Electroplating**



**silicet trio clip**

- 3 electrodes cell for 4" wafer
- Ion membrane for use with additives
- 1 µA - 3 A reverse pulse plating to extend to 100 kHz
- 2 l volume with particle filter

## Additional Technology


**Polishing Machine**



**Logitech PM5**

- Precision Polishing Jig with vacuum adapter
- Up to 4" wafer
- Plate Speed: 0-70 rpm
- Chemical Mechanical Polishing option

**Nano Electroplating**



**Nano Electroplating Cell**

- Potentiostatic and Galvanostatic Plating
- Pulse- & Reverse-Puls-Plating up to 100 kHz
- Currents down to several nA

**Micro Assembly**



**Arteos TOMM 1**

- Pic and placer
- Plate- and air-heater
- UV-curing
- Micro-dispenser
- Vacuum chuck

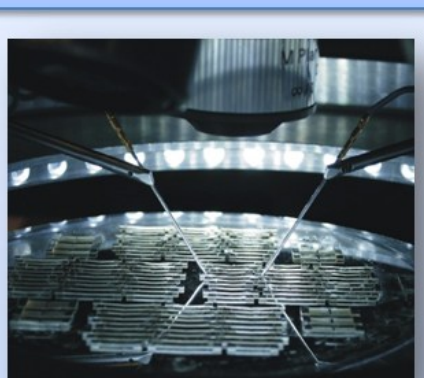
**Bond Shear Tester**



**dage Microtester 22**

- Testing strength of solder joints, wire bonds and more
- Stitch Test Failure Detection
- 20 gm & 10 kg Load
- Resolution +/- 0,5% of load

**Motion-Analyzer**



**MEMS-Analyzer**

- 2048 x 2048 Pixel
- 15 fps, 800 MBit/s
- Repeatability < 30 nm
- Force Measurements up to 1 N
- Field of View up to 11,7 x 11,7 mm<sup>2</sup>

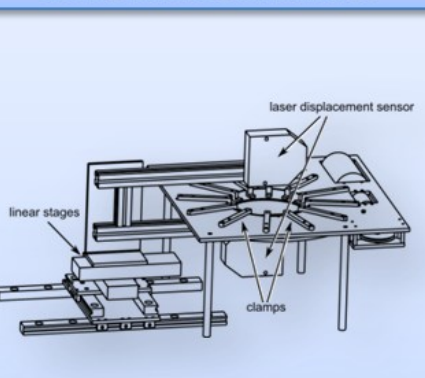
**Thermography**



**FLIR SC655**

- 640 x 480 Pixel
- 20°C to +150°C
- 0°C to 650°C
- Sensitivity: <0.05°C @ +30°C

**EAP Characterization**



**EAP-Analyzer**

- Static / dynamic deflection (line scan)
- Frequency response
- Preload simulation
- Sheet resistance
- Force-displacement

**Laser Vibrometer**



**Polytec OFV 2502**

- 2 sensor heads (OFV 534)
- Velocity demodulation
- 1.5 MHz

**Polytec OFV 3001**

- Velocity demodulation
- 0.3 µm/s...10 m/s

**High-Pressure Static Tester**



**COP-7000**

- 500 MPa=5000 bar
- silicon oil
- Room temperature

**Pressure sensor**

- P3MBP 5000 bar (HBM)

**Piston gauge**

- 5ppm @ 5 000 bar
- 1 kg / 50 bar

**High-Pressure Dynamic Tester**



**MAXIMATOR**

- up to 1000 bar
- Periodic load at 0.1 Hz to 20 Hz
- Curve shape rectangular, trapezoid or sinus
- 4 pressure connectors